



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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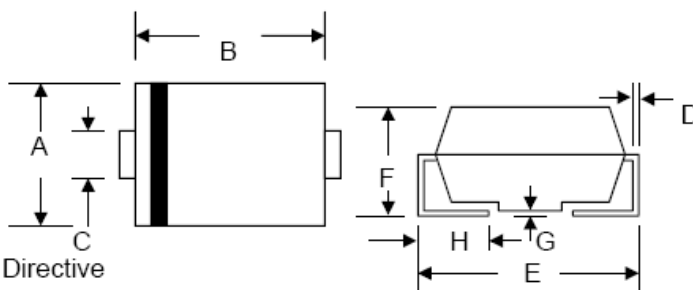


Technical Data
Data Sheet N0930, Rev. A

Green products

Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 30A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-0
- Green Products in Compliance with the RoHS Directive
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

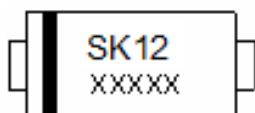


SMB/DO-214AA				
Dim	Min	Max	Min	Max
A	3.30	3.94	0.130	0.155
B	4.06	4.70	0.160	0.185
C	1.91	2.11	0.075	0.083
D	0.15	0.31	0.006	0.012
E	5.08	5.59	0.200	0.220
F	2.13	2.44	0.084	0.096
G	0.05	0.20	0.002	0.008
H	0.76	1.27	0.030	0.050
		In mm		In inch

Mechanical Data

- Case: Low Profile Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)

Marking Diagram:



Where XXXXX is YYWWL

- SK12 = Part Name
- YY = Year
- WW = Week
- L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
SK12-SK110	SMB (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

- China - Germany - Korea - Singapore - United States ●
- <http://www.smc-diodes.com> - sales@smc-diodes.com ●



SK12-SK110
1.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

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Maximum Ratings and Electrical characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	SK12	SK13	SK14	SK15	SK16	SK18	SK19	SK110	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	80	90	100	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	56	64	71	V
Average Rectified Output Current @T _L = 75°C	I _O	1.0								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30								A
Forward Voltage @ I _O = 1.0 A	V _F	0.55			0.70		0.85			V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	0.5 20								mA
Typical Thermal Resistance Junction to Ambient (Note 1)	R _{θJA}	95								K/W
Operating Temperature Range	T _J	-55 to +125								°C
Storage Temperature Range	T _{STG}	-55 to +150								°C

Note: 1. mounted on P.C. Board with 0.5mm² copper pad areas.

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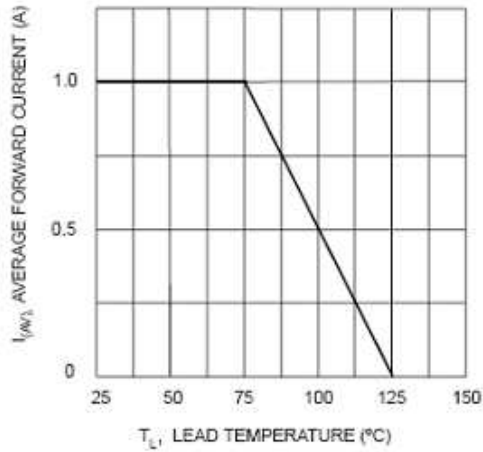


Fig. 1 Forward Current Derating Curve

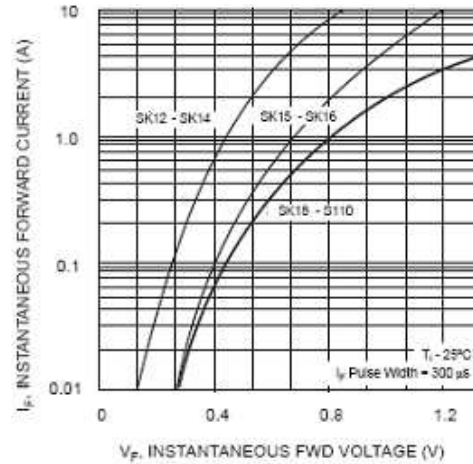


Fig. 2 Typ. Forward Characteristics

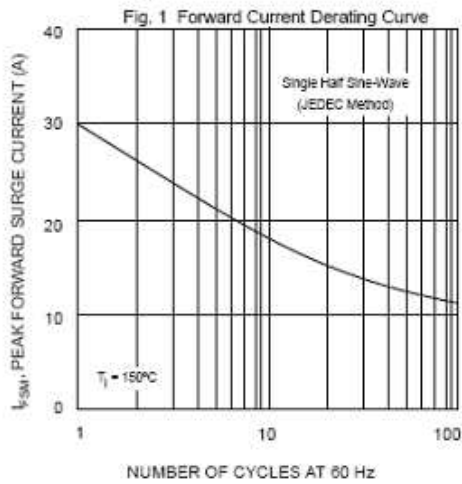


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

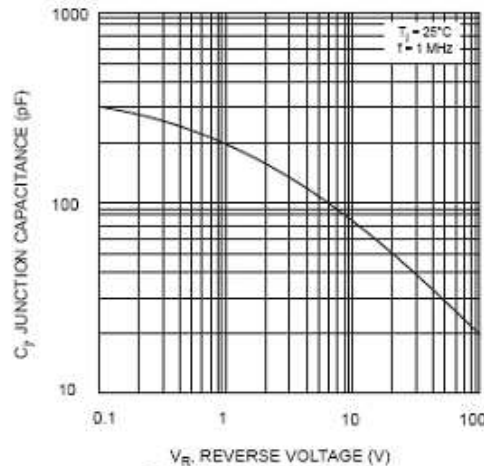


Fig. 4 Typical Junction Capacitance

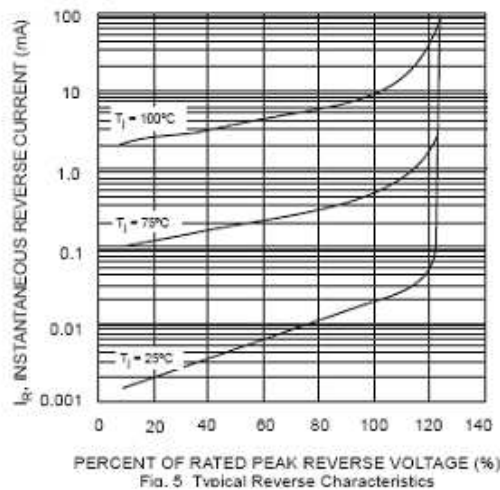


Fig. 5 Typical Reverse Characteristics



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